



**THE DATASHEET OF**  
**736560000**





Part Number : 736560000

Product Description : HDM Board-to-Board  
Backplane Power Module, Vertical, SMC,  
Power Receptacle, 3 Circuits, Gold (Au)  
0.76µm

Series Number : 73656

Status : Active

Product Category : Backplane Connectors

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## Documents & Resources

### Drawings

Drawing 736560000\_sd.pdf

Packaging Design Drawing PK-70873-0819-001.pdf

### 3D Models and Design Files

3D Model 736560000\_stp.zip

### Specifications


Application Specification AS-73656-1998-001.pdf

Product Specification PS-73670-9999-001.pdf

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## Product Environment Compliance

### Compliance

GADSL/IMDS	Not Relevant
China RoHS	
EU ELV	Not Relevant
Low-Halogen Status	Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2023)3788-DC (14 Jun 2023)
EU RoHS	Compliant per EU 2015/863

### Multiple Part Product Compliance Statements

- Eu RoHS
- REACH SVHC
- Low-Halogen

### Multiple Part Industry Compliance Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration

- IEC-62474

- chemSHERPA (xml)

EU RoHS Certificate of Compliance

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## Part Details

### General

Status	Active
Category	Backplane Connectors
Series	73656
Description	HDM Board-to-Board Backplane Power Module, Vertical, SMC, Power Receptacle, 3 Circuits, Gold (Au) 0.76µm
Application	Backplane
Comments	Backplane Power Module
Component Type	Power Header
Product Family	HDM Backplane Connector System
Product Name	HDM
UPC	800754345361

### Agency

CSA	LR19980
UL	E29179

### Electrical

Current - Maximum per Contact	15.0A
Data Rate	1.0 Gbps
Voltage - Maximum	500V AC

### Physical

Circuits (Loaded)	3
Circuits (maximum)	3
Color - Resin	Black
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0

Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Beryllium Copper
Material - Plating Mating	Gold
Material - Plating Termination	Gold
Material - Resin	High Temperature Thermoplastic
Net Weight	1.609/g
Number of Columns	1
Number of Pairs	Open Pin Field
Number of Rows	3
Orientation	Vertical
Packaging Type	Tube
PC Tail Length	3.50mm
PCB Locator	No
PCB Retention	Yes
PCB Thickness - Recommended	2.50mm
Pitch - Mating Interface	3.70mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	0.051µm
Polarized to PCB	No
Stackable	Yes
Temperature Range - Operating	-55° to +105°C
Termination Interface Style	Through Hole - Compliant Pin

### Solder Process Data

Lead-Free Process Capability	N/A
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## Looking for pricing, stock, or lifecycle information?

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 [Molex, LLC Information](#)

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